

PACKAGED SEMICONDUCTOR DEVICE HAVING STACKED DIE

ABSTRACT OF THE DISCLOSURE

5 A method for forming a packaged semiconductor device and a
packaged semiconductor device. A first semiconductor die is coupled to a
package substrate. Wire bonds are then coupled to the first semiconductor
die and to the package substrate. Encapsulant is applied such that the
encapsulant extends over the first semiconductor die and over the wire
10 bonds. The encapsulant is then at least partially cured. A second
semiconductor die is coupled to the encapsulant. The second semiconductor
die is electrically coupled to the ball grid array substrate. Encapsulant is then
applied and cured to form a second layer of encapsulant that covers the
second semiconductor die.